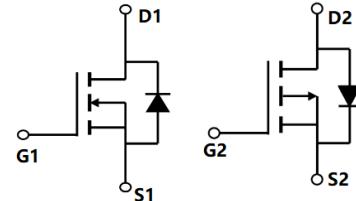
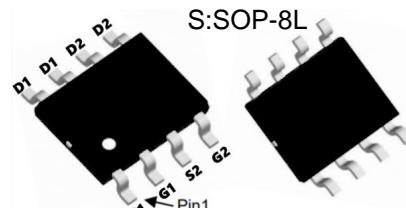
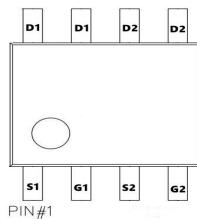


TM024G04S

N+P-Channel Enhancement Mode Mosfet

General Description <ul style="list-style-type: none"> • Low $R_{DS(ON)}$ • RoHS and Halogen-Free Compliant Applications <ul style="list-style-type: none"> • Load switch • PWM 	Product Summary <p>N Channel $V_{DS} = 40V$, $I_D = 8A$ $R_{DS(ON)} = 24m\Omega$ (typ.) @ $V_{GS} = 10V$</p> <p>P Channel $V_{DS} = -40V$, $I_D = -7A$ $R_{DS(ON)} = 35m\Omega$ (typ.) @ $V_{GS} = -10V$</p> <p>100% UIS Tested 100% R_g Tested</p>
--	--



Marking: 08G04 OR 4614B

Absolute Maximum Ratings ($T_c = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating		Units
		N-Ch	P-Ch	
V_{DS}	Drain-Source Voltage	40	-40	V
V_{GS}	Gate-Source Voltage	± 20	± 20	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	8	-7	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	4.2	-4.2	A
I_{DM}	Pulsed Drain Current ²	26	-24	A
EAS	Single Pulse Avalanche Energy ³	16.2	39	mJ
$P_D @ T_A = 25^\circ C$	Total Power Dissipation ⁴	1.67	1.67	W
T_{STG}	Storage Temperature Range	-55 to 150	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	57		$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	30		$^\circ C/W$

TM024G04S
N+P-Channel Enhancement Mode Mosfet
N-Channel Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	40	44	---	V
$\Delta BVDSS/\Delta T_J$	BVDSS Temperature Coefficient	Reference to 25°C , $I_D=1\text{mA}$	---	0.034	---	$\text{V}/^{\circ}\text{C}$
RDS(ON)	Static Drain-Source On-Resistance ²	$V_{GS}=10\text{V}$, $I_D=5\text{A}$	---	24	35	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$, $I_D=4\text{A}$	---	36	49	
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250\mu\text{A}$	1.5	2.5	3.5	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	-4.56	---	$\text{mV}/^{\circ}\text{C}$
IDSS	Drain-Source Leakage Current	$V_{DS}=32\text{V}$, $V_{GS}=0\text{V}$, $T_J=25^{\circ}\text{C}$	---	---	1	μA
		$V_{DS}=32\text{V}$, $V_{GS}=0\text{V}$, $T_J=55^{\circ}\text{C}$	---	---	5	
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$	---	---	± 100	nA
gfs	Forward Transconductance	$V_{DS}=5\text{V}$, $I_D=5\text{A}$	---	14	---	S
R _g	Gate Resistance	$V_{DS}=0\text{V}$, $V_{GS}=0\text{V}$, f=1MHz	---	2.6	---	Ω
Q _g	Total Gate Charge (4.5V)	$V_{DS}=20\text{V}$, $V_{GS}=4.5\text{V}$, $I_D=5\text{A}$	---	5.5	---	nC
Q _{gs}	Gate-Source Charge		---	1.25	---	
Q _{gd}	Gate-Drain Charge		---	2.5	---	
Td(on)	Turn-On Delay Time	$V_{DD}=20\text{V}$, $V_{GS}=10\text{V}$, $R_G=3.3\Omega$ $I_D=1\text{A}$	---	8.9	---	ns
T _r	Rise Time		---	2.2	---	
Td(off)	Turn-Off Delay Time		---	41	---	
T _f	Fall Time		---	2.7	---	
C _{iss}	Input Capacitance	$V_{DS}=15\text{V}$, $V_{GS}=0\text{V}$, f=1MHz	---	593	---	pF
C _{oss}	Output Capacitance		---	76	---	
C _{rss}	Reverse Transfer Capacitance		---	56	---	
I _s	Continuous Source Current ^{1,5}	$V_G=V_D=0\text{V}$, Force Current	---	---	6.1	A
ISM	Pulsed Source Current ^{2,5}		---	---	23	A
VSD	Diode Forward Voltage ²	$V_{GS}=0\text{V}$, $I_S=1\text{A}$, $T_J=25^{\circ}\text{C}$	---	---	1.2	V

Note :

- 1、The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3、The EAS data shows Max. rating . The test condition is $V_{DD}=25\text{V}$, $V_{GS}=10\text{V}$, $L=0.1\text{mH}$, $I_{AS}=10\text{A}$
- 4、The power dissipation is limited by 150°C junction temperature
- 5、The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

TM024G04S
N+P-Channel Enhancement Mode Mosfet
P-Channel Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=-250\mu\text{A}$	-40	---	---	V
$\Delta BVDSS/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=-1\text{mA}$	---	-0.02	---	$\text{V}/^{\circ}\text{C}$
RDS(ON)	Static Drain-Source On-Resistance ²	$V_{GS}=-10\text{V}$, $I_D=-5\text{A}$	---	35	48	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$, $I_D=-3\text{A}$	---	49	68	
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=-250\mu\text{A}$	-1.5	-2.5	-3.5	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	3.72	---	$\text{mV}/^{\circ}\text{C}$
IDSS	Drain-Source Leakage Current	$V_{DS}=-32\text{V}$, $V_{GS}=0\text{V}$, $T_J=25^{\circ}\text{C}$	---	---	1	uA
		$V_{DS}=-32\text{V}$, $V_{GS}=0\text{V}$, $T_J=55^{\circ}\text{C}$	---	---	5	
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$	---	---	± 100	nA
Q_g	Total Gate Charge (-4.5V)	$V_{DS}=-20\text{V}$, $V_{GS}=-4.5\text{V}$, $I_D=-6\text{A}$	---	15.8	---	nC
Q_{gs}	Gate-Source Charge		---	3.5	---	
Q_{gd}	Gate-Drain Charge		---	3.2	---	
Td(on)	Turn-On Delay Time	$V_{DD}=-15\text{V}$, $V_{GS}=-10\text{V}$, $R_G=3.3\Omega$, $I_D=-1\text{A}$	---	5.2	---	ns
T_r	Rise Time		---	7	---	
Td(off)	Turn-Off Delay Time		---	23	---	
T_f	Fall Time		---	8	---	
C_{iss}	Input Capacitance	$V_{DS}=-15\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$	---	1000	---	pF
C_{oss}	Output Capacitance		---	160	---	
C_{rss}	Reverse Transfer Capacitance		---	100	---	
Is	Continuous Source Current ^{1,5}	$V_G=V_D=0\text{V}$, Force Current	---	---	-5.7	A
VSD	Diode Forward Voltage ²	$V_{GS}=0\text{V}$, $I_S=-1\text{A}$, $T_J=25^{\circ}\text{C}$	---	---	-1.2	V

Note :

- 1、The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3、The EAS data shows Max. rating . The test condition is $V^{DD}=-25\text{V}$, $V^{GS}=-10\text{V}$, $L=0.1\text{mH}$, $I^{AS}=-7\text{A}$
- 4、The power dissipation is limited by 150°C junction temperature
- 5、The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

TM024G04S

N+P-Channel Enhancement Mode Mosfet

N-Channel Typical Characteristics

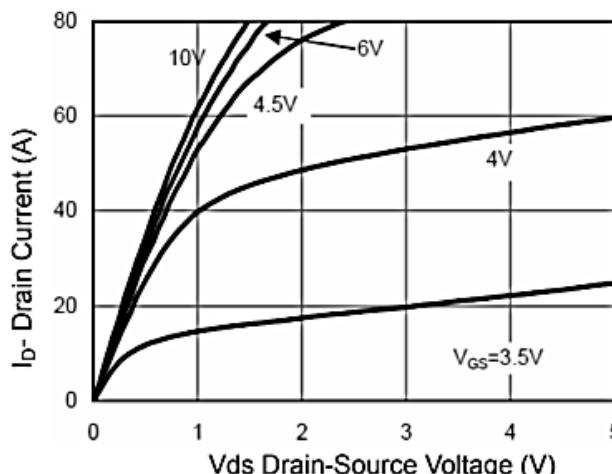


Figure 1 Output Characteristics

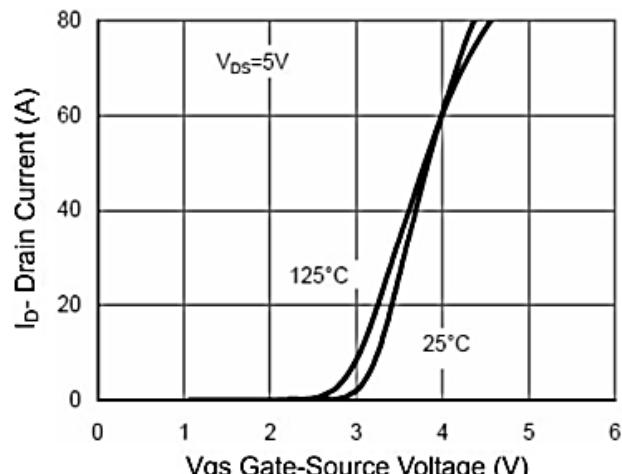


Figure 2 Transfer Characteristics

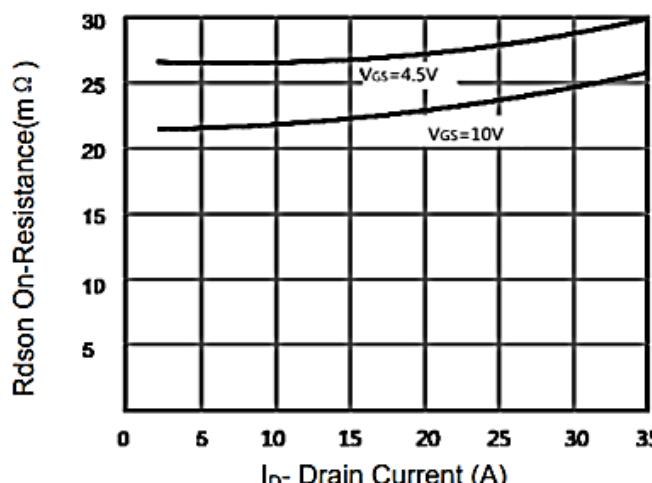


Figure 3 Rdson- Drain Current

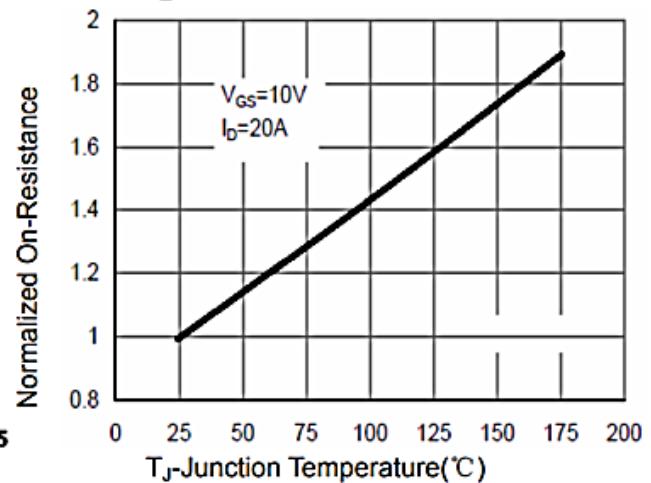


Figure 4 Rdson-JunctionTemperature

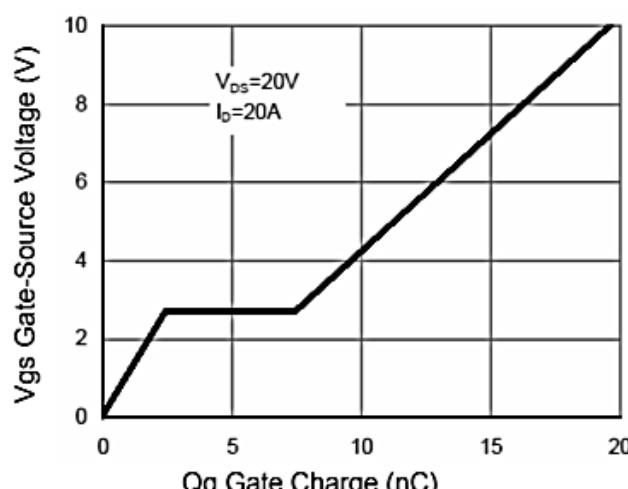


Figure 5 Gate Charge

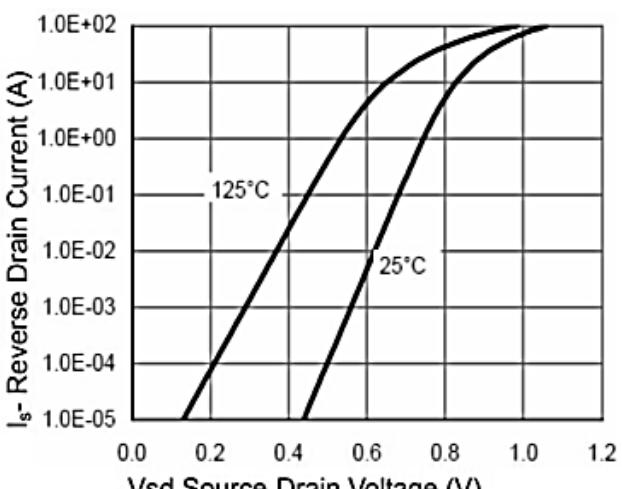


Figure 6 Source- Drain Diode Forward

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N+P-Channel Enhancement Mode Mosfet

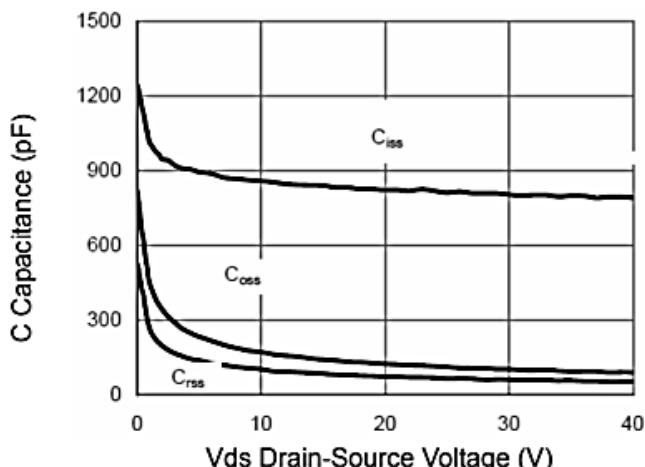


Figure 7 Capacitance vs Vds

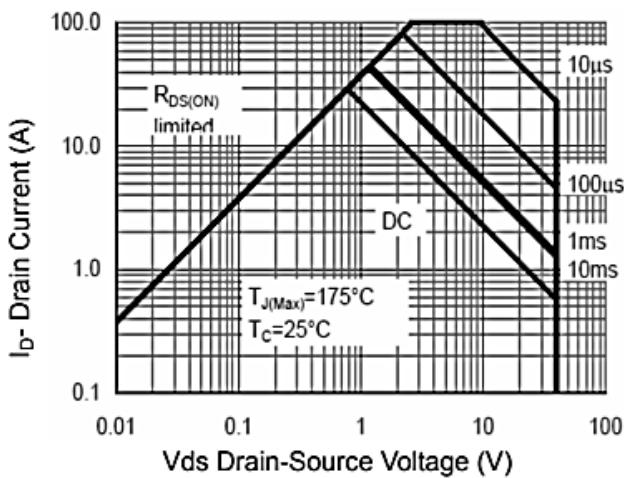


Figure 8 Safe Operation Area

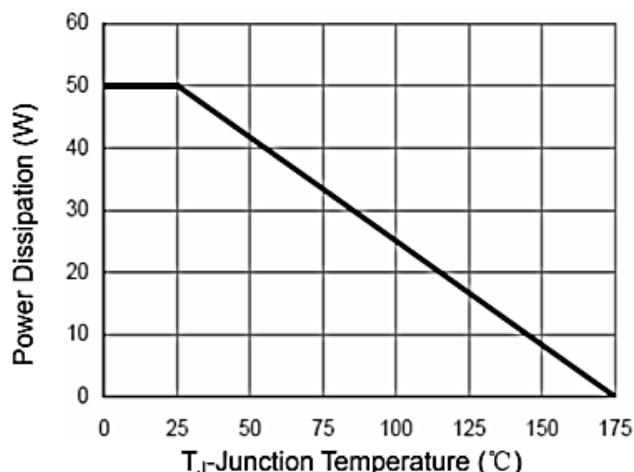


Figure 9 Power De-rating

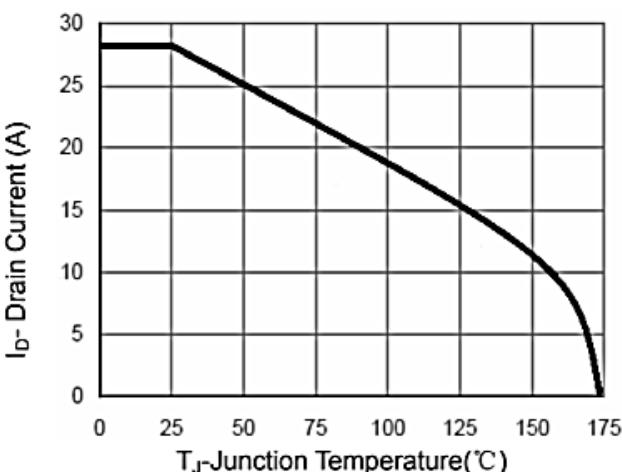


Figure 10 I_D Current De-rating

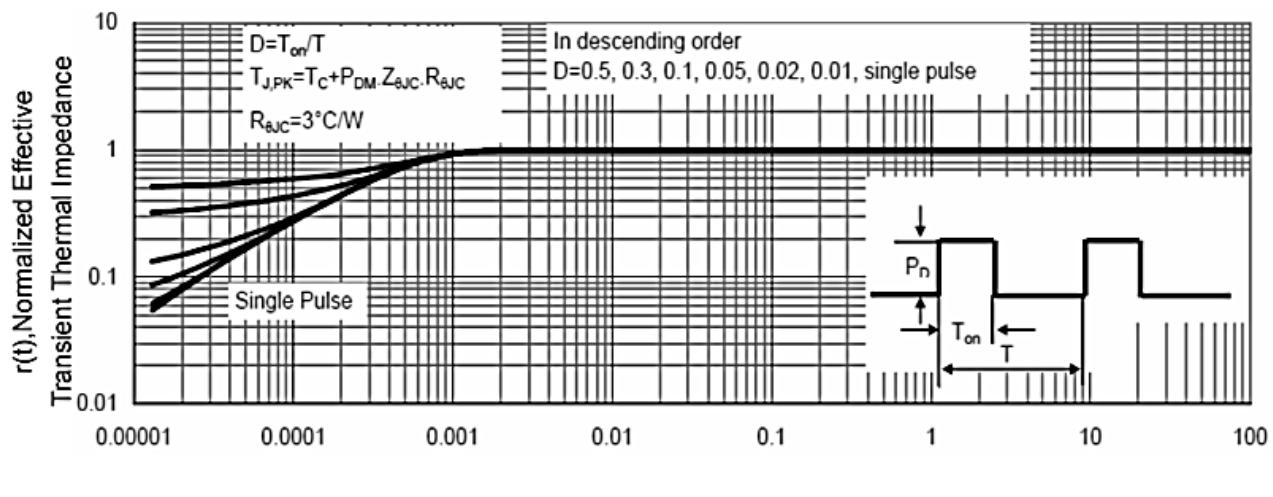


Figure 11 Normalized Maximum Transient Thermal Impedance

TM024G04S

N+P-Channel Enhancement Mode Mosfet

P-Channel Typical Characteristics

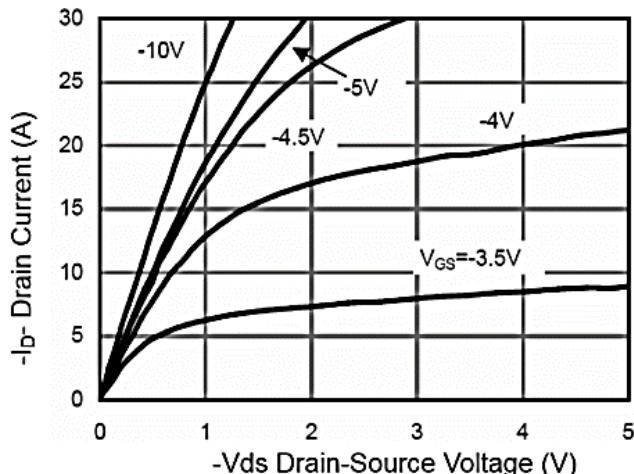


Figure 1 Output Characteristics

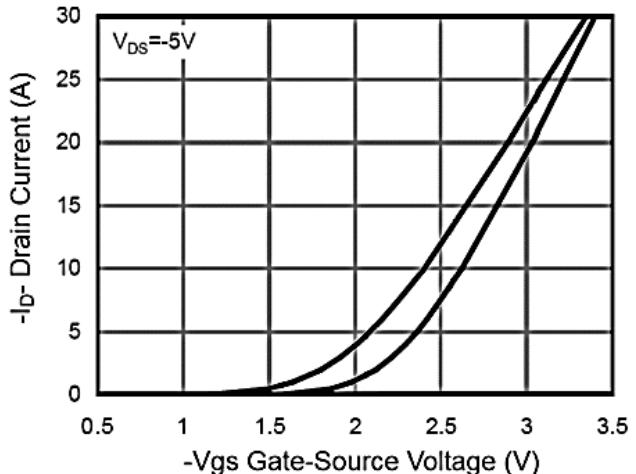


Figure 2 Transfer Characteristics

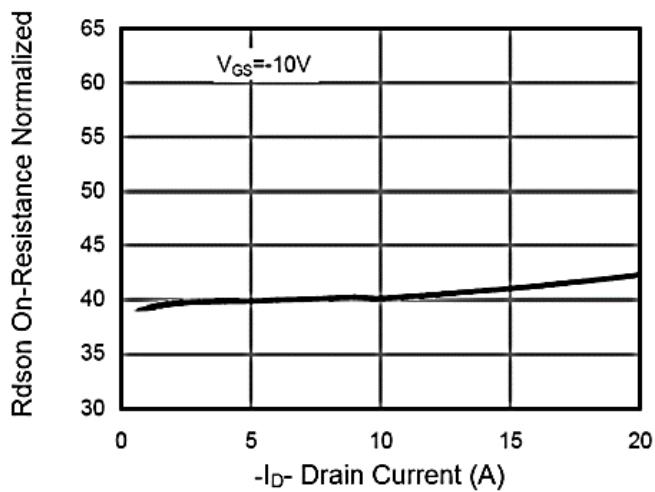


Figure 3 Rdson- Drain Current

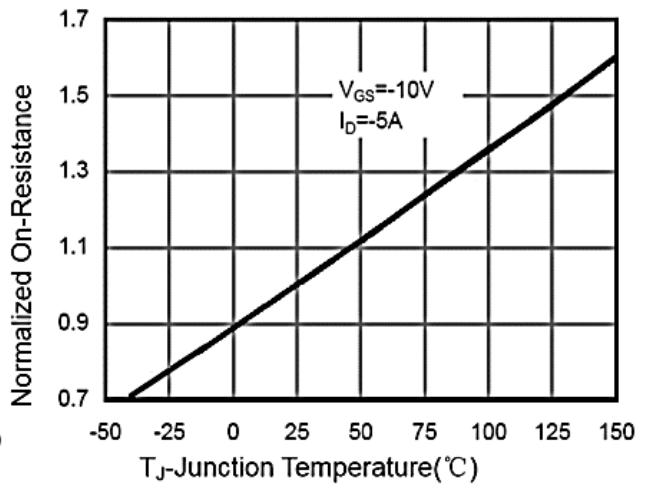


Figure 4 Rdson-Junction Temperature

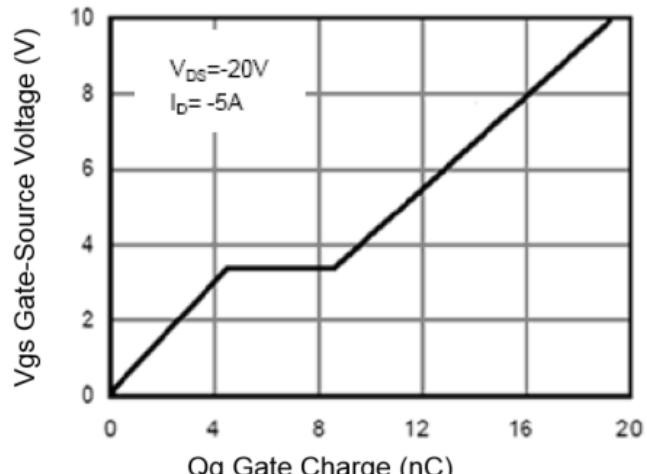


Figure 5 Gate Charge

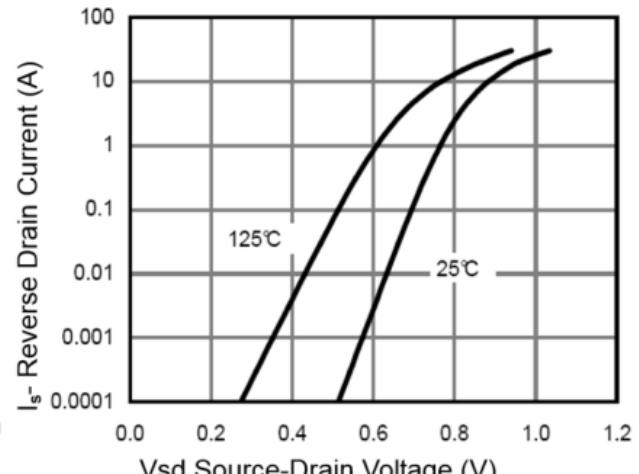


Figure 6 Source- Drain Diode Forward

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N+P-Channel Enhancement Mode Mosfet

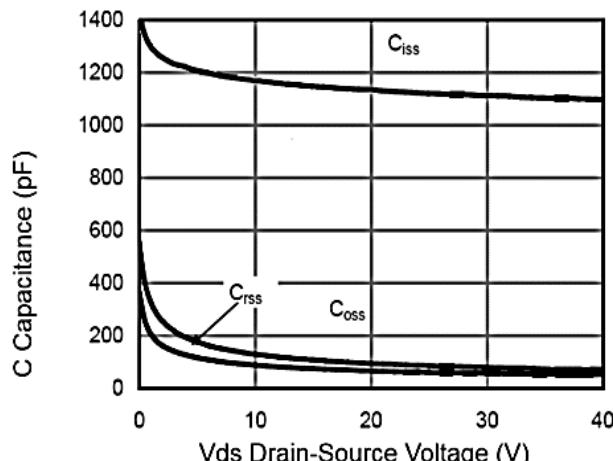


Figure 7 Capacitance vs V_{ds}

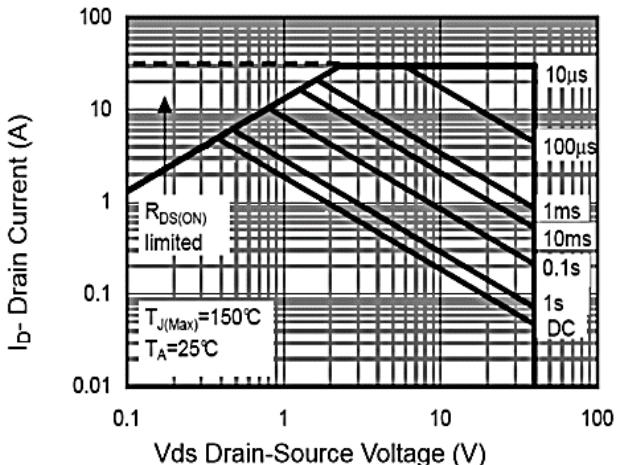


Figure 8 Safe Operation Area

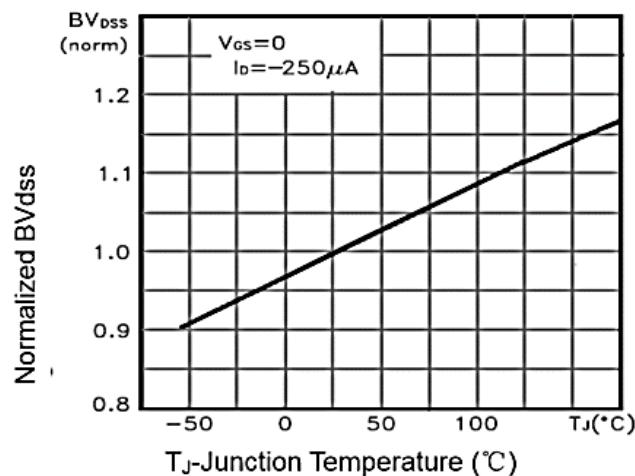


Figure 9 BV_{dss} vs Junction Temperature

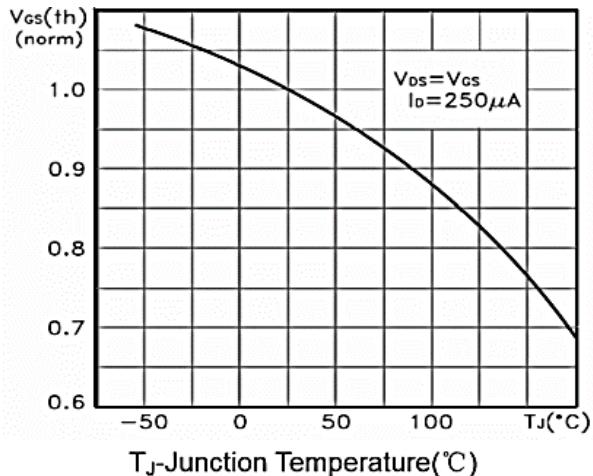


Figure 10 V_{gs(th)} vs Junction Temperature

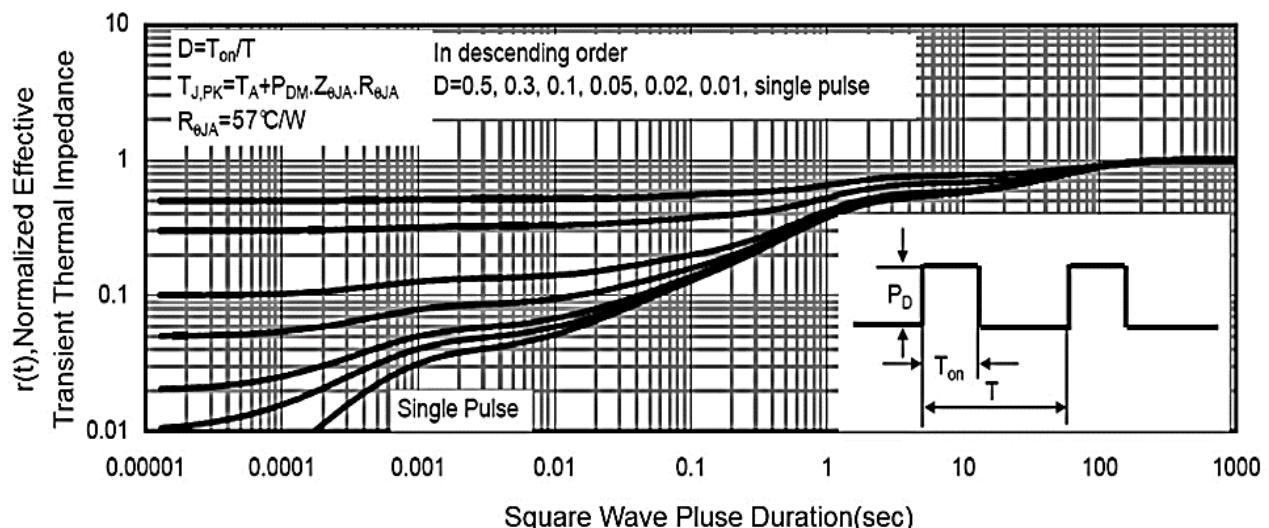
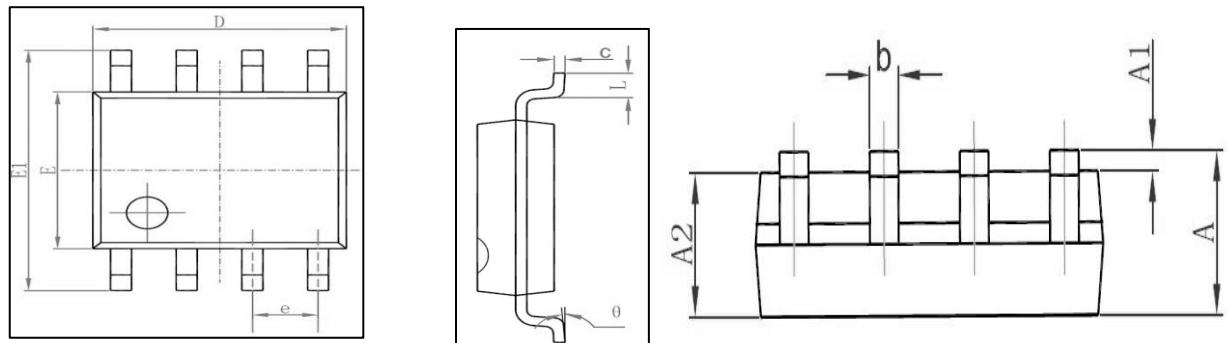
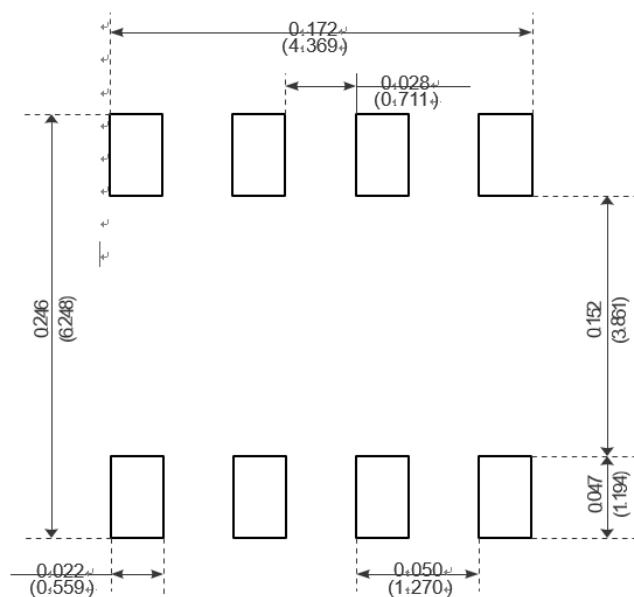


Figure 11 Normalized Maximum Transient Thermal Impedance

Package Mechanical Data:SOP-8L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°



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